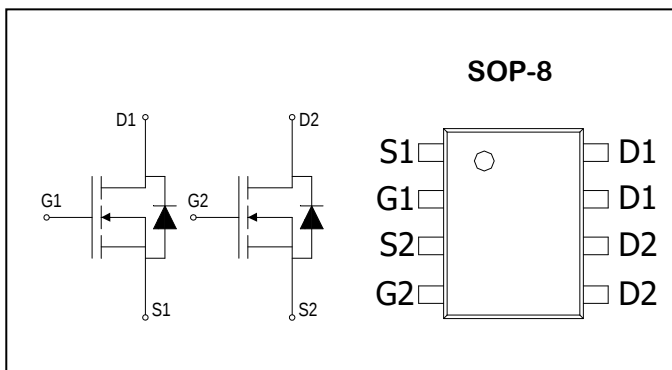


**Dual N-Channel Enhancement Mode Field Effect Transistor****PRODUCT SUMMARY**

| $V_{DSS}$ | $I_D$ | $R_{DS(ON)}$ (m $\Omega$ ) |
|-----------|-------|----------------------------|
| 30V       | 9A    | 15m $\Omega$               |

**Absolute Maximum Ratings** (  $T_A = 25^\circ\text{C}$  unless otherwise specified )

| Symbol                     | Parameter                           |                      | Ratings    | Unit |
|----------------------------|-------------------------------------|----------------------|------------|------|
| Common Ratings             |                                     |                      |            |      |
| V <sub>DSS</sub>           | Drain-Source Voltage                |                      | 30         | V    |
| V <sub>GSS</sub>           | Gate-Source Voltage                 |                      | ±20        |      |
| T <sub>J</sub>             | Maximum Junction Temperature        |                      | 150        | °C   |
| T <sub>STG</sub>           | Storage Temperature Range           |                      | -55 to 150 | °C   |
| I <sub>S</sub>             | Diode Continuous Forward Current    | T <sub>C</sub> =25°C | 2.3        | A    |
| Mounted on Large Heat Sink |                                     |                      |            |      |
| I <sub>DM</sub>            | 300μs Pulse Drain Current Tested(1) | T <sub>C</sub> =25°C | 30         | A    |
| I <sub>D</sub>             | Continuous Drain Current            | T <sub>C</sub> =25°C | 9          | A    |
| P <sub>D</sub>             | Maximum Power Dissipation           |                      | 2.5        | W    |

1. Pulse width limited by maximum junction temperature.

**Thermal Characteristics**

| Symbol     | Parameter                               | Ratings | Unit               |
|------------|-----------------------------------------|---------|--------------------|
| $R_{thJC}$ | Thermal resistance junction-case max    | 40      | $^\circ\text{C/W}$ |
| $R_{thJA}$ | Thermal resistance junction-ambient max | 50      | $^\circ\text{C/W}$ |

**Electrical Characteristics** (TA=25°C Unless Otherwise Noted)

| Symbol                    | Parameter                                     | Test conditions                                           | Min. | Typ. | Max.  | Unit |
|---------------------------|-----------------------------------------------|-----------------------------------------------------------|------|------|-------|------|
| On/off Characteristics    |                                               |                                                           |      |      |       |      |
| BV <sub>DSS</sub>         | Drain-Source Breakdown Voltage                | V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA               | 30   | --   | --    | V    |
| I <sub>DSS</sub>          | Zero Gate Voltage Drain Current               | V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V                | --   | --   | 10    | uA   |
| V <sub>GS(th)</sub>       | Gate Threshold Voltage                        | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA | 1.0  | --   | 2.5   | V    |
| I <sub>GSS</sub>          | Gate Leakage Current                          | V <sub>GS</sub> =± 20V, V <sub>DS</sub> =0V               | --   | --   | ± 100 | nA   |
| R <sub>DS(ON)</sub>       | Drain-SourceOn-stateResistance <sup>(2)</sup> | V <sub>GS</sub> = 10V, I <sub>DS</sub> =8A                | --   | 15   | 20    | mΩ   |
| g <sub>FS</sub>           | Forward transconductance <sup>(2)</sup>       | V <sub>DS</sub> = 10V, I <sub>DS</sub> =8A                | --   | 15   | --    | S    |
| Dynamic Characteristics   |                                               |                                                           |      |      |       |      |
| C <sub>iss</sub>          | Input Capacitance                             | V <sub>GS</sub> =0V,                                      | --   | 350  | 420   | pF   |
| C <sub>oss</sub>          | Output Capacitance                            | V <sub>DS</sub> = 25V,                                    | --   | 55   | --    |      |
| C <sub>rss</sub>          | Reverse Transfer Capacitance                  | Frequency=1.0MHz                                          | --   | 35   | --    |      |
| Switching Characteristics |                                               |                                                           |      |      |       |      |
| t <sub>d(ON)</sub>        | Turn-on Delay Time <sup>(1)</sup>             | V <sub>DD</sub> =15V,                                     | --   | 8    | --    | ns   |
| t <sub>r</sub>            | Turn-on Rise Time <sup>(1)</sup>              | I <sub>D</sub> = 1A, V <sub>GS</sub> = 10V,               | --   | 7    | --    |      |
| t <sub>d(OFF)</sub>       | Turn-off Delay Time <sup>(1)</sup>            | R <sub>GEN</sub> =3.3 Ω                                   | --   | 15   | --    |      |
| t <sub>f</sub>            | Turn-off Fall Time <sup>(1)</sup>             |                                                           | --   | 5    | --    |      |
| Q <sub>g</sub>            | Total Gate Charge <sup>(1)</sup>              | V <sub>DS</sub> =15V, V <sub>GS</sub> = 4.5V,             | --   | 4.1  | --    | nC   |
| Q <sub>gs</sub>           | Gate-Source Charge <sup>(1)</sup>             | I <sub>DS</sub> =8A                                       | --   | 1.1  | --    |      |
| Q <sub>gd</sub>           | Gate-Drain Charge <sup>(1)</sup>              |                                                           | --   | 2.5  | --    |      |
| Diode Characteristics     |                                               |                                                           |      |      |       |      |
| V <sub>SD</sub>           | Diode Forward Voltage <sup>(2)</sup>          | I <sub>SD</sub> = 1A, V <sub>GS</sub> = 0V                | --   | --   | 1.0   | V    |
| t <sub>rr</sub>           | Reverse Recovery Time                         | I <sub>SD</sub> =8A, dI <sub>SD</sub> /dt=100A/μs,        | --   | 15   | --    | ns   |
| q <sub>rr</sub>           | Reverse Recovery Charge                       | V <sub>GS</sub> = 0V                                      | --   | 14   | --    | nC   |

## NOTES:

1. Independent of operating temperature.
2. Pulse Test : Pulse width ≤ 300 μs, Duty cycle ≤ 2%

## Typical Performance Characteristics

Figure 1: Continuous Drain Current vs.  $T_C$

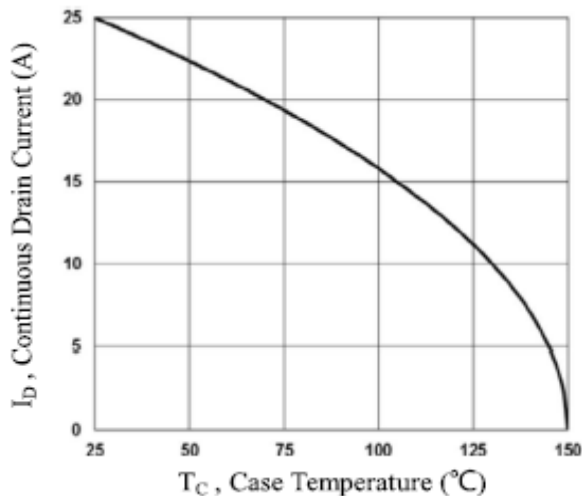


Figure 2: Normalized  $R_{DS(on)}$  vs.  $T_J$

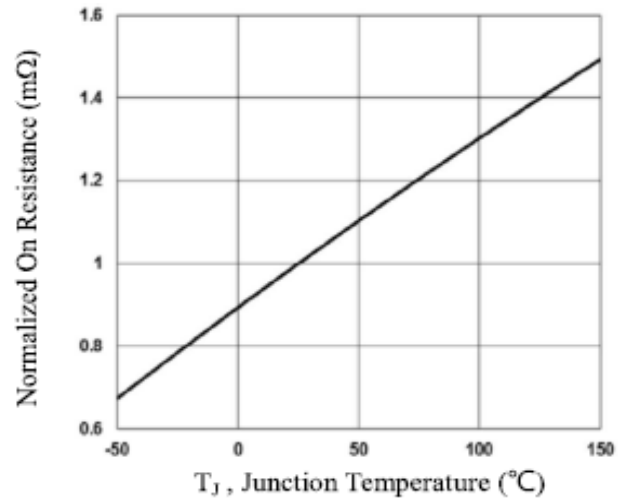


Figure 3: Gate Charge Characteristics

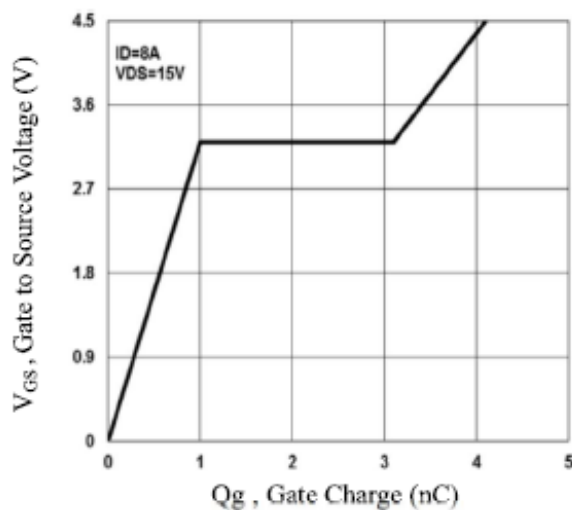


Figure 4: Normalized  $V_{GS(th)}$  vs.  $T_J$

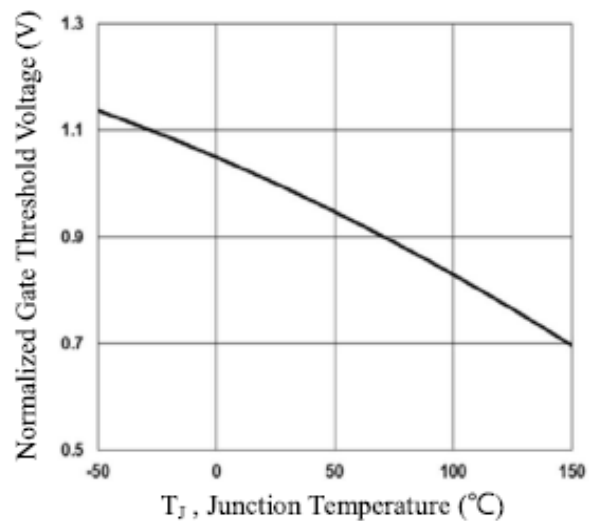


Figure 5: Normalized Transient Response

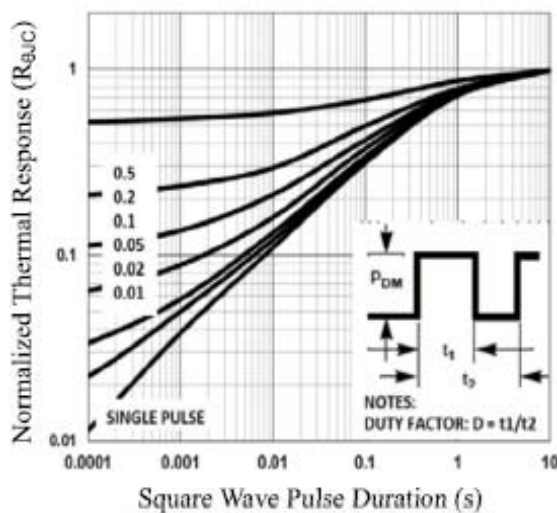
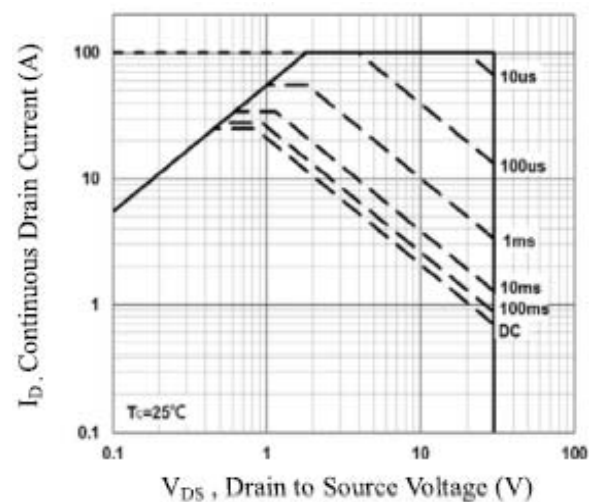
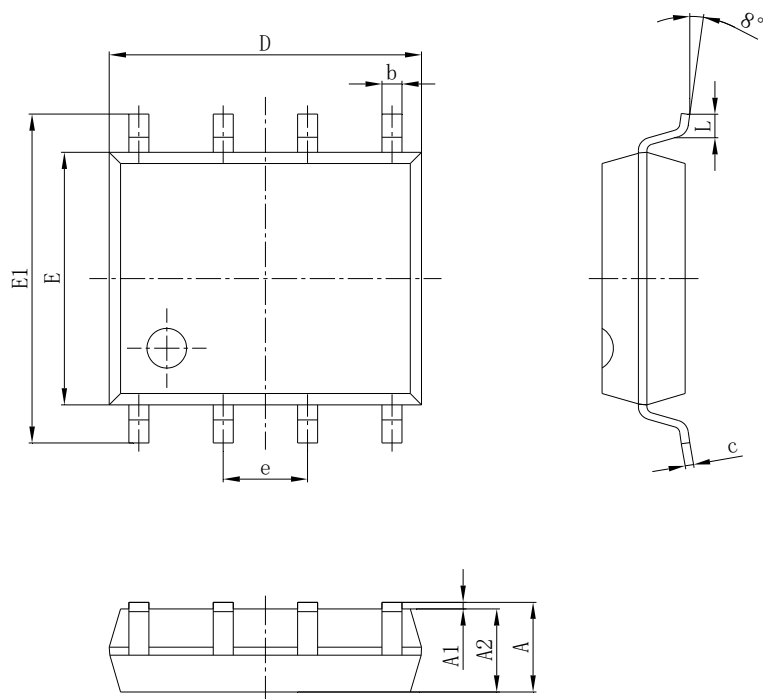


Figure 6: Safe Operating Area



## PACKAGE MECHANICAL DATA

### SOP-8 Package Dimension



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| e      | 1.270TYP                  |       | 0.050TYP             |       |
| e1     | 4.500                     | 4.700 | 0.177                | 0.185 |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |